



SOD323 Diodes

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Frame 33.3414%	Nickel	7440-02-0	0.6300	41.05	136,956.5
	Manganese	7439-96-5	0.0123	0.80	2,667.4
	Cobalt	7440-48-4	0.0077	0.50	1,667.0
	Silicon	7440-21-3	0.0046	0.30	1,000.0
	Phosphorus	7723-14-0	0.0004	0.02	83.0
	Sulfur	7704-34-9	0.0004	0.02	83.0
	Carbon	7440-44-0	0.0008	0.05	167.0
	Iron	7439-89-6	0.8787	57.25	191,013.0
	Silver	7440-22-4	0.0002	0.01	33.0
	Total			1.5349	
Chip 0.9850%	Silicon	7440-21-3	0.04531	100.00	9,850.0
	Total			0.0453	
Bonding Wire 0.1477%	Copper	7440-50-8	0.0066	98.37	1,434.8
	Palladium	7440-5-3	0.0001	1.49	21.7
	Gold	7440-57-5	0.0000	0.14	2.0
	Total			0.0067	
Molding 62.7187%	Silica	60676-86-0	2.1926	76.00	476,652.2
	Epoxy resin	Trade Secret	0.2885	10.00	62,717.4
	Phenolic resin	29690-82-2	0.2164	7.50	47,043.5
	Brominated Resin	40039-93-8	0.0866	3.00	18,815.2
	Antimony trioxide	1309-64-4	0.0866	3.00	18,815.2
	Carbon Black	1333-86-4	0.0144	0.50	3,130.4
	Total			2.8850	
Plating 2.8072%	Tin	7440-31-5	0.1291	100.00	28,065.2
	Total			0.1291	
Total mass (mg)			4.60		